

X8060

Universal
2D/3D X-ray inspection



MXI+ μ CT

X-ray inspection for larger inspection objects

Semi-automatic X-ray inspection in 2D and 3D Modes

**2D and 3D inspection
without mechanical conversion**

**Designed for larger, heavier
inspection objects**

**Precision manipulator with
up to 8 CNC-capable axes**

**High magnification with
angled radiation**

**Convenient, direct positioning
by clicking on optical
overview image**

**Fast, accurate 2D measurement
process independent
of magnification**

**Microfocus computed tomography
(μ CT) for volume reconstruction**

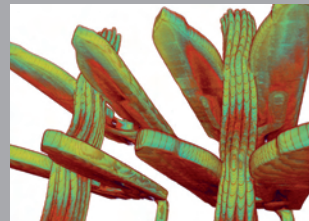
**Independent, real-time image pro-
cessing with Viscom analysis tools**

**Realistic 3D volume model
with measurement in
all spatial directions**

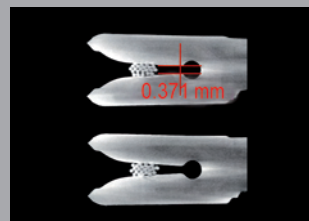
**Excellent image quality through
high-contrast resolution**

X-ray inspection delivers information about the interior of a 3D inspection object. Even in 2D mode, quick, highly magnified views of the third dimension are possible. But with the help of modern computed tomography, the 3D mode allows the reconstruction of complete volumetric models, allowing non-destructive slices to be made or measurements taken in any direction.

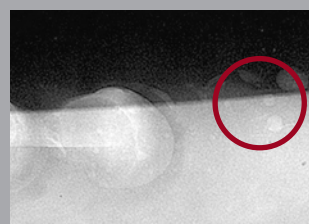
This flexibility makes the X8060 a valuable inspection tool for various industrial applications. Typical defects recognized by this non-destructive process are tears, bridges, pores, voids, foreign bodies, form deviations, incorrect positioning, misalignment, or inhomogeneous material transitions.



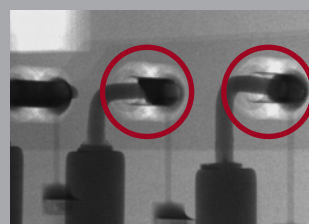
Clamping joints,
3D volume reconstruction



Clamping joints, 3D slice
reconstruction with
distance measurement



Defective aluminium
weld seam



Defective THT solder joints

X8060 – the flexible μ CT-system

The X8060 was developed for **destruction-free inspection** in industrial and scientific settings. The **typical application areas** of the X8060 are characterized by the system's ability to handle not only large or heavy inspection objects, but also to inspect the smallest parts, with the highest magnification.

Optional **microfocus computed tomography (μ CT)** enables 3D inspection and visualization of the inspection object. Along with the spatial assignment of production defects and material flaws, individual slices or section images can also be visualized with this process. Due to its exceptional spatial display capabilities, the μ CT improves defect localization and enables direct measurement within the volumetric model.

The system's **8-axis manipulator** opens up entirely new possibilities for angled radiation with high magnification. The structure of hidden solder joints in electronic assemblies, such as with BGAs, is revealed, and larger inspection objects can be inspected with the same system. These multiple application possibilities save costs and increase system utilization. A **real-time image processing system** provides all image refinements without time lag, allowing the operator to concentrate fully on the inspection task.

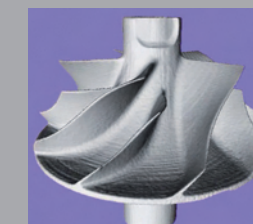
The core of the X-ray technology is a high-capacity, open **microfocus X-ray tube**, designed to provide highest flexibility, outstanding image quality and stable in-line operation. Its user-friendly design guarantees a practically unlimited service life and quick, easy maintenance, minimizing costs.

Viscom specializes in automatic inspection. A wide selection of **Viscom's own analysis tools** are also available for the X8060.

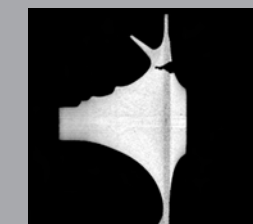
μ CT: Microfocus computed tomography of a turbine rotor



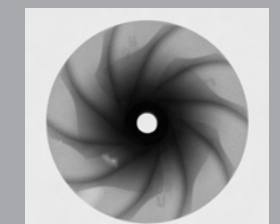
Optical view



3D volume
reconstruction



Non-destructive
3D slice through
a casting defect



2D X-ray image,
casting defects

Technical Specifications

X8060-16 | X8060-20 | X8060-22 | X8060-25

X-ray technology

X-ray tube	Open all-metal Viscom tube, series XT9000 with reflection or transmission target			
High voltage	10 - 160 kV	10 - 200 kV	10 - 225 kV	10 - 250 kV
Tube current	5 - 1000 μ A or 5 - 3000 μ A			
Target load	Max. 40 W/500 W			
Detail recognition	< 2 μ m / < 1 μ m			
Magnification	Direct geometric magnification without collimator > 4000 x			
Image intensifier	High-resolution digital flat panel detectors (12/14/16 bit)			
Option	0 - 60° angled view with digital flat panel detector			
X-ray cabinet	In compliance with the German X-Ray Regulations (RöV) regarding fully protected devices. Leakage radiation < 1 μ Sv/h			

Software

User interface	Viscom XMC
Option	BGA analysis BGA-S Pore analysis software (void calculation) ACA-S THT analysis software THT-S Wire sweep analysis software WSA-S μ CT module for all available detectors listed above

System computer

Operating system	Windows®
Processor	Intel® Core™ i7

Sample handling

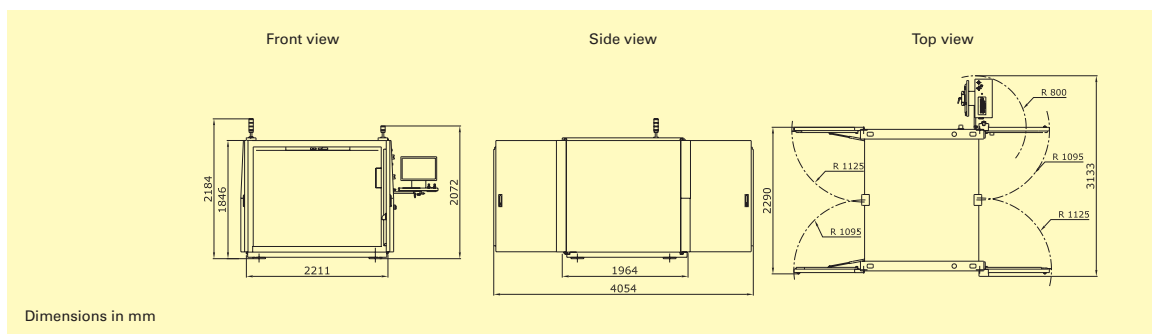
Manipulator	4 axes (X, Y, Z and rotation n x 360°)
Horizontal X/Y-axis	Travel range: 610 x 460 mm (24.0" x 18.1")
Vertical Z-axis	Travel range: 800 mm (31.5")
Detector axis (option)	60° pivoting, variable detector distance, travel range: 700 mm (27.6")
Tilt axis	\pm 60° option
Max. sample size X/Y	660 x 510 mm (26.0" x 20.1") (L x W)
Max. sample weight	30 kg (66 lbs), with option tilt axis 10 kg (22 lbs)
Test piece change	Pneumatic front window
Option	Pneumatic front slide door
CT axis	Standard

Inspection speed

Variable

Other system data

Power requirements	400 V (other voltages on request), 3P/N/PE, 8 A
System dimensions	2211 x 1846 x 1964 mm (87.0" x 72.7" x 77.3") (W x H x D)
Weight	Approx. 4000 kg (8818 lbs)



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